



AFML-TR-78-128

PITTING CORROSION AND SURFACE CHEMICAL PROPERTIES OF A THIN OXIDE LAYER ON ANODIZED ALUMINUM ALLOYS



MECHANICS AND SURFACE INTERACTIONS BRANCH NONMETALLIC MATERIALS DIVISION

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FOREWORD

This technical report was prepared by Neil McDevitt and William L. Baun, Mechanics and Surface Interactions Branch, Nonmetallic Materials Division, Air Force Materials Laboratory (AFML/MBM), Wright-Patterson Air Force Base, Ohio, and Mr. James S. Solomon, University of Dayton Research Institute, Dayton, Ohio. The work was initiated under Project 2419, "Nonmetallic and Composite Materials", and was administered by the Air Force Materials Laboratory, Air Force Systems Command, Wright-Patterson Air Force Base, Ohio.

This report covers work conducted inhouse during the period June 1977 through May 1978. The report was released by the author in August 1978.

The authors are especially grateful to Mr. Brewster Stroop for his helpful advice and efforts in obtaining the SEM micrographs.

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SECTION I

BACKGROUND

The importance of metal-to-metal adhesive bonding technology has been established for secondary structural members of present day aircraft. Continued interest in this type of fabrication has led to a program to utilize bonded materials as primary structural components of airframes. This emphasis on primary structures necessitates a continuing research effort in this overall area in order to improve the life expectancy of these materials under real life service conditions.

In order to determine the average life expectancy of a bonded component, the present day researcher is confronted with a complex number of factors to consider. Factors to be considered cross a number of interdisciplinary technologies: (1) all components of the adhesive joint, (2) dynamic environment evaluation, and (3) mechanics of failure analysis. We propose the following breakdown of the above areas into specific study efforts as follows:

A. Components of the Adhesive Joint

1) metallurgy of the aluminum alloy.

- 2) surface chemistry of the adherend.
- 3) prepared oxide layer.
- 4) primer chemistry.
- 5) chemistry of the adhesive system.
- 6) chemistry of the cure cycle.
- 7) synergism of each created interface.

- B. Dynamic Environment
 - 1) stress.
 - 2) humidity and other atmospheric gases.
 - 3) temperature.
- C. Failure Analysis
 - 1) fracture.
 - 2) fatigue.
 - 3) corrosion.

The appropriate permutations and combinations of A, B, and C should generate a data base capable of advancing our knowledge in the area of life expectancy of adhesively bonded primary structural components of airframes.

SECTION II

INTRODUCTION

Numerous publications on the mechanical properties of metal-tometal adhesive bonds have shown the effect of the organic resin or primer on bond strength. With the advent of surface instrumentation technology, the effects of the chemical aspects of bonded joints are now being studied (Reference 1). Presently the interface receiving the most attention by surface analysis techniques is the adhesive-oxide interface.

The present paper presents a selection of results obtained from studies designed to generate data from the oxide-metal interface. This particular interface is normally overlooked in the failure analysis of a bonded joint. However, the probability of the cause of structural failure due to bond line corrosion can be high in certain environments. This probability arises from the fact the high strength 2000 and 7000 series aluminum alloys used by the aircraft industry are less corrosion resistant than most of the other aluminum alloys. When the aluminum industry uses these alloys as structural materials they alleviate this problem by cladding (essentially a thin film of commercial grade aluminum placed on the bulk surface). These films are designed to be anodic with respect to the bulk alloy and therefore provide sacrificial protection in corrosive environments. This technique cannot be used when the alloys are adhesively bonded since loss of the sacrificial cladding would mean loss of bond line. The aircraft industry is then required to work with these alloys in the so called "bare" state with the chemical composition as shown in Table 1.

In present day adhesive bonding technology one of the first steps used in the surface preparation of these bare materials is to protect, or passivate, the surface with an anodic thin oxide film. One method is to grow the thin

oxide film electrochemically using phosphoric acid as an electrolyte. It is highly desirable the thin oxide film retain its passivation and adhesive properties while under the influence of stress and environment.

The purpose of this study is to determine what effects the alloying constituents may have on the formation of the anodic oxide film and its passivation properties.

SECTION III

EXPERIMENTAL

1. Surface Preparation

Test materials were cut (25mm x 50mm x 1mm) from comme reially available, bare and clad, 2024-T3 and 7075-T6 aluminum. The specimens were acetone wiped, ultrasonically cleaned with carbon tetrachloride for 5 minutes, and then acid pickled. The acid pickle solution consisted of 170 ml of nitric acid, 30 ml of hydrofluoric acid, and distilled water to make one liter. Specimens were submerged for two minutes at room temperature. The effects of these treatments on the alloy surface have been studied previously (Reference 2). The specimens were anodized for 10 minutes at 10 volts using 1.0M phosphoric acid as the electrolyte.

2. Corrosion Solution

Most organic solvents by themselves do not attack aluminum alloys at room temperature; however, a solution containing a mixture of carbon tetrachloride and methanol (Reference 3) is quite reactive at room temperature with aluminum alloys containing copper. Our mixture contained 2 parts (by volume) carbon tetrachloride and one part methanol. Specimens were observed submerged in the corrosion solution using a microscope at 100X.

3. Instrumentation

After removal from the corrosion solution identification of the major elemental species present on the surface or in the **corrosion pits was** made through the use of Ion Scattering Spectroscopy (ISS), Secondary Ion Mass Spectroscopy (SIMS), Auger Electron Spectroscopy (AES), and Scanning Electron Microscopy (SEM). A description of the first three techniques is reported in Reference 1. Most researchers are familiar with the SEM technique (Reference 4); however, we also have attached to our SEM

system an energy dispersive x-ray detector. With this equipment x-rays can be collected and counted as a function of their energy. In this manner, x-rays from different elements can be collected and the displayed energy spectra will be directly related to the kind of element present in the sample being analyzed.

SECTION IV

RESULTS AND DISCUSSION

We know the chemical properties of the generated anodic oxide film can vary as a function of alloying constituents and chemical surface treatments (Reference 2).

Wood (Reference 5) has reported on the incorporation of alloying elements in the anodic oxide layer of thick (50 μ m) films. Our studies (Reference 6) on thin anodic oxide films show the same general trend where alloying elements become part of the growing oxide film. We can see some of these effects in Figure 1 where a HNO₃-HF treated surface of 2024Al was anodized for 60 seconds in H₃PO₄. This oxide film is approximately 0.05 μ m thick, but the elements fluorine and copper are still detected by SIMS and ISS. Since these chemical inhomogenieties can exist throughout the oxide film it is necessary to know if they can be responsible for breakdown of the passive film.

Each specimen was placed individually in the corrosion solution and observed with the use of a binocular microscope. Corrosion was allowed to take place at open circuit potentials. Primary attack on each specimen was recognized at discrete points on the surface by the onset of a stream of bubbles. When the area under observation had initiated 3 to 5 pits the specimen was removed from the solution and rinsed with methanol, then distilled water and dried at 150° F under a heat lamp. What makes this corrosion solution particularly interesting is the fact that pure aluminum, aluminum oxide, and aluminum hydroxide are not readily attacked at room temperature. Therefore, the pitting that occurs will only take place through defects in the anodic oxide film formed on 2024 and 7075. A typical corrosion pit area (Figure 2) is shown in the SEM micrograph. The pit area is then marked and a chemical analysis performed on

them with the surface instrumentation described in Reference 1. It is obvious (Figure 3) that the oxide film is not attacked by the corrosion solution since it continues to support itself across the area that has suffered pit corrosion. Because we allowed pit growth to occur only for a short time most of the corrosion pits were covered with oxide film. This is essentially the same type of pit configuration and growth observed by Bargeron and Givens (Reference 7); however, their pit growth was initiated by short duration low voltage pulses in comparison to our open circuit potential study.

Figure 4 shows an SEM micrograph of a corrosion pit produced on 2024 aluminum. The pit in this case has no oxide film covering the area. There appear to be small spherical growth products at the bottom of this pit. The electron beam from our Auger spectrometer can be focused into this pit allowing us to obtain an elemental chemical analysis of this area. The data obtained from this pit (Figure 5) shows copper with a large peak to peak intensity with the amplifier sensitivity set at 4X. Some magnesium and manganese are also detected. A pit was formed on a 7075 aluminum specimen and analyzed (Figure 6). The elements copper, zinc, and magnesium were detected. 7075 aluminum contains approximately 5.5% zinc; however, only a small amount is detected in the pit. Auger data obtained outside a pit (Figure 7) was used as a reference point for the elements found within the pit. Elements of primary interest detected outside the pit, are aluminum and oxygen. Figure 8 is an x-ray image of the pit shown in Figure 4. The image depicts the data from the x-ray system set to accept energies for the element copper. The bright images indicate the presence of copper (Reference 8) in the spherical products at the bottom of the pit. Figure 9 shows a mosaic of micrographs. The upper right corner is an SEM electron picture of a pit generated on a 7075 aluminum specimen. The other three micrographs represent x-ray images. The upper left shows the

image obtained from the element chlorine, lower left aluminum, and lower right for copper. Very little chlorine is detected in the pit. We had expected to see larger amounts of chlorine since Vorster (Reference 2) proposed the primary corrosion reaction to be:

2 C1 ⁻ + Cu	$Cu Cl_2 + e^-$	(1)
$CuCl_2 + 2Cl$	$Cu Cl_2 + e^-$ $\left[Cu Cl_4\right]^- + e^-$	(2)

Examination of pits on other specimens showed very small amounts of chlorine detected. Our corrosion solution is a 2:1 mixture of CCL_4 : CH_3OH . If the ratio is reversed $(2CH_3OH):CCl_4$) the corrosion rate increases dramatically. The latter solution would represent a large decrease in chloride ion concentration; therefore, it is difficult to understand why the corrosion rate increases if reactions 1 and 2 are the controlling factors. Further work is necessary to better understand the complex chemistry that must be present in this mixture with respect to its corrosive attack on copper containing aluminum alloys.

The clad specimens required a much longer time period (compared to the bare material) in the corrosion solution in order to start pit formation. This was expected since the corrosion solution reacts very slowly with a pure aluminum film^{*} at room temperature. Examination of the pits that eventually occurred showed selective dissolution of certain grain boundaries. An SEM micrograph of one of these pits formed on the surface of 2024 clad aluminum is shown in Figure 10. A similar pit was obtained from a 7075 clad specimen (Figure 11). Neither x-ray energy data or Auger electron spectra detected any of the alloying constituents in the pit. Aluminum and oxygen were the only elements detected. The 7075 cladded material was the first to pit. The 2024 clad specimen required a scratch to initiate a pit formation.

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* containing <1% copper.

SECTION V

SUMMARY AND CONCLUSIONS

The more important structural aluminum alloys, bare 2024 and 7075, used in the aircraft industry were found to react readily with a solution formed from a mixture of organic solvents, methanol and carbon tetrachloride. This same solution does not react with pure aluminum, aluminum oxide or aluminum hydroxide. The differences in these reaction rates allowed us to use this solution as a corrosion environment for studying anodic oxide film defects formed on these alloys.

A small number of corrosion pits were allowed to grow to approximately 100-micron diameter. This required an 8 to 10 minute time duration. None of the alloying constituents were observed by Auger spectroscopy external to the pits in this time period. Data obtained from within the pits by Auger and SEM-x-ray scans show copper is always present. Magnesium and zinc were detected in the pits of some of the specimens. From this study it is apparent that pit initiation occurs at defects created in the anodic oxide film by the alloying constituents.

In particular we can see that copper present as microparticles or the intermetallic compound CuAl₂ can cause defects in the formed anodic oxide film. These defects are then potential sites for pit corrosion. This chain of events will reduce the long-term service quality of an adhesively bonded structure. This particular interface, the oxide-metal interface, merits more attention from researchers and theorists concerned with metalto-metal adhesively bonded structures.

SECTION VI

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TABLE 1

Chemical Composition of 2024 and 7075 Aluminum

n Si Ti Al	.0.9 0.5 Remainder	3 0.5 0.2 Remainder
Cr Mn	0.10 0.3-0.9	0.1-0.4 0.3
Zn Fe	0.25 0.50	5.1-6.1 0.7
Cu Mg	3.8-4.9 1.2-1.8	1.2-2.0 2.1-2.9 5.1-6.1
Alloy	2024	7075

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Figure 2. SEM Electron Micrograph of a Typical Pit Corrosion Area













Figure 8. X-Ray Image of Copper Obtained from the Pit Shown in Figure 4



Figure 9. Mosaic of SEM Data. Starting Upper Right Going Clockwise; SEM Electron Image of 7075 Pit Formation, X-Ray Image of Copper, X-Ray Image of Aluminum, X-Ray Image of Chlorine



Figure 10. Corrosion Pit Formed on Clad 2024 Showing Preferential Etching of Pit



Figure 11. Corrosion Pit Formed on Clad 7075 Preferential Etching of Pit

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